L Number	Hits	Search Text	DB	Time stamp
-	43	("6232147" "6455408" "5910644" "6501165"	USPAT;	2004/04/16 10:28
		"6620633" "6620731" "5792594" "6218281"	US-PGPUB;	, , , , , , , , , , , , , , , , , , , ,
		"5567981" "6388333" "6064112" "6403457"	EPO; JPO;	
		"6232147" "6335104" "6355104" "6396148"	DERWENT;	
1		"6303424" "6372624" "6380555" "6127736"	IBM_TDB	
		"6451624" "6303524").pn.	_	
-	1362	(bond or bonding or wirebond or stud near2	USPAT;	2004/04/14 15:30
		bump or solder near2 ball or ball near2	US-PGPUB;	
		grid) near10 (nickel or vanadium or chromium	EPO; JPO;	
		or copper or ni or v or cr or cu or crcu)	DERWENT;	
		near10 (gold or au or platinum or pt or	IBM_TDB	
		palladium or pd or non-oxidizing or		
		nonoxidizing) same (redistribution or redistributing or trace or lead or path)		
_	205		USPAT;	2004/04/14 16:09
	203	bump or solder near2 ball or ball near2	US-PGPUB;	2004/04/14 10:05
		grid) near8 (nickel or vanadium or chromium	EPO; JPO;	
		or copper or ni or v or cr or cu or crcu)	DERWENT;	
		near8 (gold or au or platinum or pt or	IBM_TDB	
		palladium or pd or non-oxidizing or	_	
		nonoxidizing) same (redistribution or		
		redistributing or trace)		
-	22	("3761782" "4074342" "4670770"	USPAT	2004/04/14 15:43
		"4709468" "4829014" "4890157"		
		"4948754" "5106461" "5137845"		
		"5198684" "5219117" "5224265"		
		"5246880"		
		"5436411" "5502002" "5505366"		
		"5604379" "5677576" "5719448"		
	220	"5851911").PN.	HCDAT.	2004/04/15 16:35
_	228	(redistribution or redistributing) same (wirebond or wirebonding or wire adj bond or	USPAT; US-PGPUB;	2004/04/15 16:35
		wire adj bonding or solder adj ball or	EPO; JPO;	
		conductive adj ball or ball adj grid or	DERWENT;	
		solder adj bump or conductive adj bump) with	IBM TDB	
		(pad or electrode)	_	
_	0	(redistribution or redistributing) near3	USPAT;	2004/04/15 15:02
		(stack or laminate or laminated) same	US-PGPUB;	
		(wirebond or wirebonding or wire adj bond or	EPO; JPO;	
		wire adj bonding or solder adj ball or	DERWENT;	
		conductive adj ball or ball adj grid or	IBM_TDB	
		solder adj bump or conductive adj bump) with		
		(pad or electrode)	HODAT	2004/04/25 25 21
_	14	(redistribution or redistributing) near3 (stack or laminate or laminated) and	USPAT;	2004/04/15 15:04
		(wirebond or wirebonding or wire adj bond or	US-PGPUB; EPO; JPO;	
		wire adj bonding or solder adj ball or	DERWENT;	
		conductive adj ball or ball adj grid or	IBM_TDB	
		solder adj bump or conductive adj bump) with		
		(pad or electrode)		
-	130	1 -	USPAT;	2004/04/15 16:33
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_	6400100 HDDV	IBM_TDB	2004/04/25 22 22
_		6492198.URPN.	USPAT	2004/04/16 11:03
-	0	(nonoxidizing or non-oxidizing or wettable) near6 (gold or au) near6 electroless\$ and	USPAT;	2004/04/15 16:34
		(barrier or ubm) near6 (nickel or ni) near6	US-PGPUB; EPO; JPO;	
		electroless\$	DERWENT;	
			IBM TDB	
_	34	(wirebond or wirebonding or wire adj bond or	USPAT;	2004/04/15 16:39
		wire adj bonding or solder adj ball or	US-PGPUB;	
		conductive adj ball or ball adj grid or	EPO; JPO;	
		solder adj bump or conductive adj bump)	DERWENT;	
]		near6 (pad or electrode) near10 (barrier or	IBM_TDB	
		ubm) and (barrier or ubm or nickel) near6		
	L	(electroless\$ or electro-less\$)		

-	45	(wirebond or wirebonding or wire adj bond or	USPAT;	2004/04/15 16:41
		wire adj bonding or solder adj ball or	US-PGPUB;	
		conductive adj ball or ball adj grid or	EPO; JPO;	
		solder adj bump or conductive adj bump)	DERWENT;	
		near6 (pad or electrode) near10 (barrier or	IBM TDB	
		ubm) and (barrier or ubm or nickel or ni or	1 -	
		gold or au or wettable or non-oxidizing or		
		nonoxidizing) near6 (electroless\$ or		
		electro-less\$)		